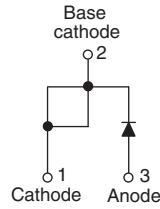
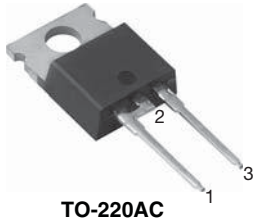


Hyperfast Rectifier, 8 A FRED Pt[®]



FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY	
Package	TO-220AC
$I_{F(AV)}$	8 A
V_R	600 V
V_F at I_F	1.3 V
t_{rr} typ.	18 ns
T_J max.	175 °C
Diode variation	Single die

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 144\text{ °C}$	8	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$	90	
Repetitive peak forward current	I_{FM}		16	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
		$I_F = 8\text{ A}$	-	2.0	2.4	
Forward voltage	V_F	$I_F = 8\text{ A}, T_J = 150\text{ °C}$	-	1.3	1.8	
		$V_R = V_R$ rated	-	0.3	50	
Reverse leakage current	I_R	$T_J = 150\text{ °C}, V_R = V_R$ rated	-	55	500	μA
			-			
Junction capacitance	C_T	$V_R = 600\text{ V}$	-	17	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t _{rr}	I _F = 1 A, dI _F /dt = 100 A/μs, V _R = 30 V	-	18	-	ns	
		I _F = 8 A, dI _F /dt = 100 A/μs, V _R = 30 V	-	20	-		
		T _J = 25 °C	-	25	-		
		T _J = 125 °C	-	40	-		
Peak recovery current	I _R RM	I _F = 8 A dI _F /dt = 200 A/μs V _R = 390 V	T _J = 25 °C	-	2.4	-	A
			T _J = 125 °C	-	4.8	-	
Reverse recovery charge	Q _{rr}		T _J = 25 °C	-	25	-	nC
			T _J = 125 °C	-	120	-	
Reverse recovery time	t _{rr}	T _J = 125 °C	I _F = 8 A dI _F /dt = 600 A/μs V _R = 390 V	-	33	-	ns
Peak recovery current	I _R RM			-	12	-	A
Reverse recovery charge	Q _{rr}			-	220	-	nC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C
Thermal resistance, junction to case	R _{thJC}		-	1.4	2	°C/W
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC	8ETH06H			

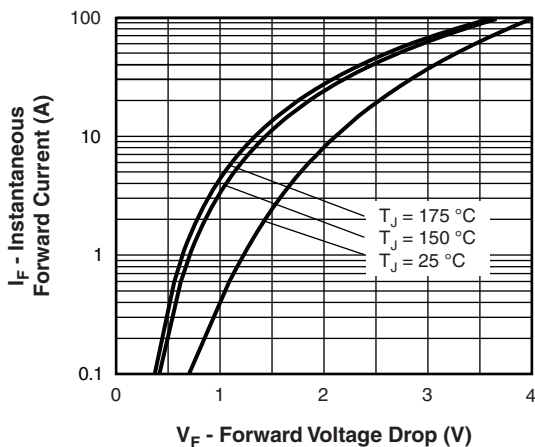


Fig. 1 - Typical Forward Voltage Drop Characteristics

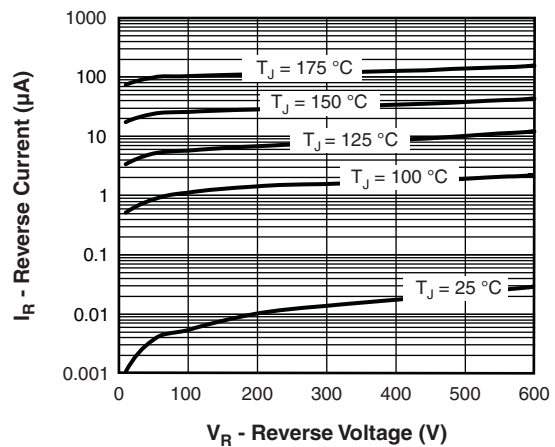


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

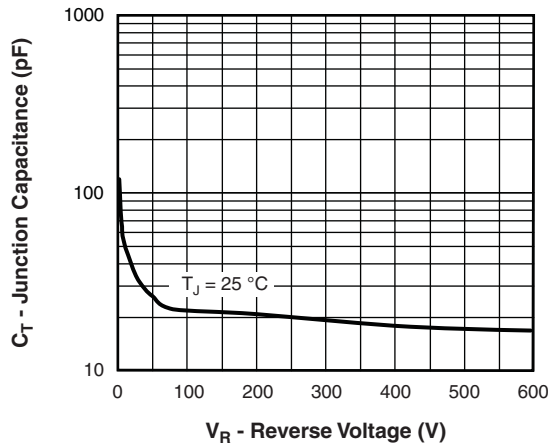


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

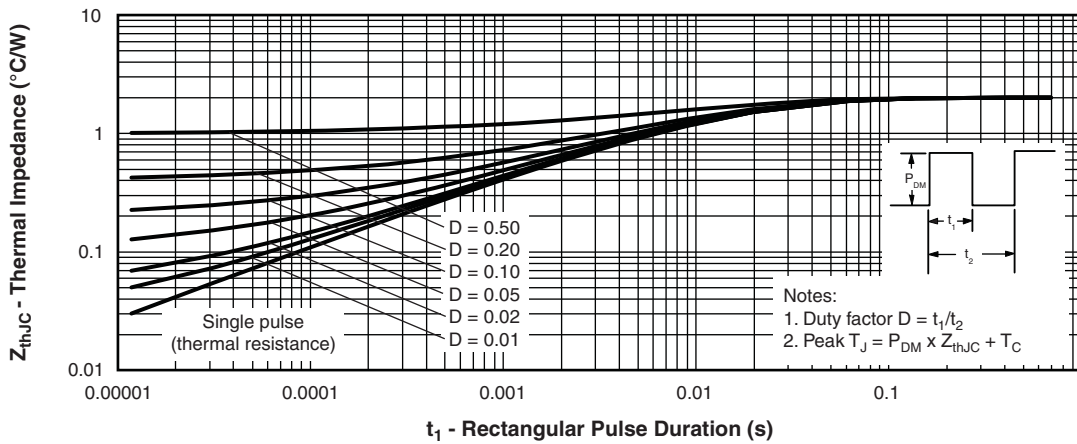


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

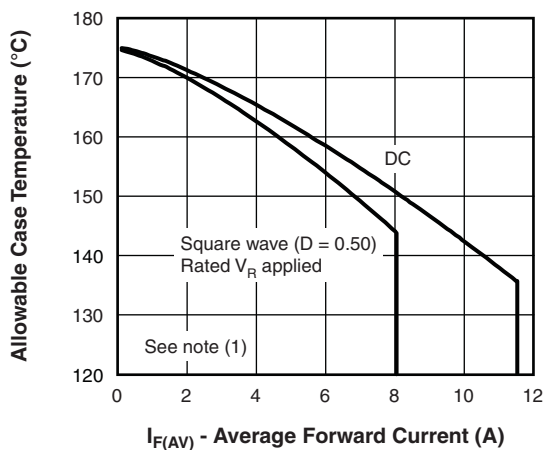


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

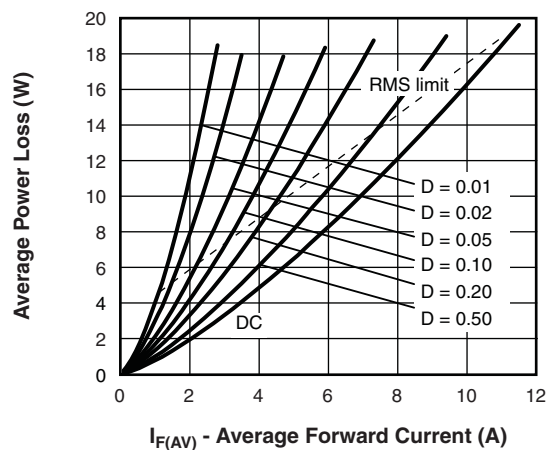


Fig. 6 - Forward Power Loss Characteristics

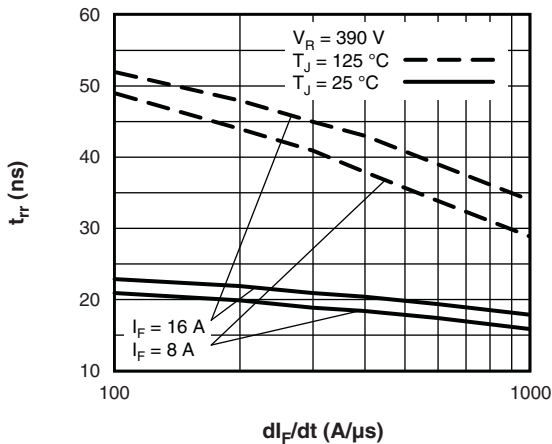


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

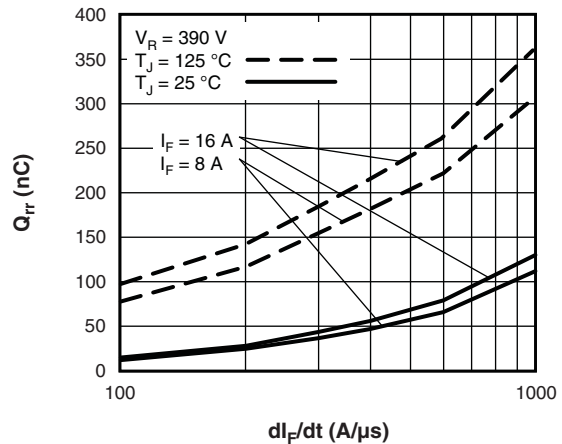
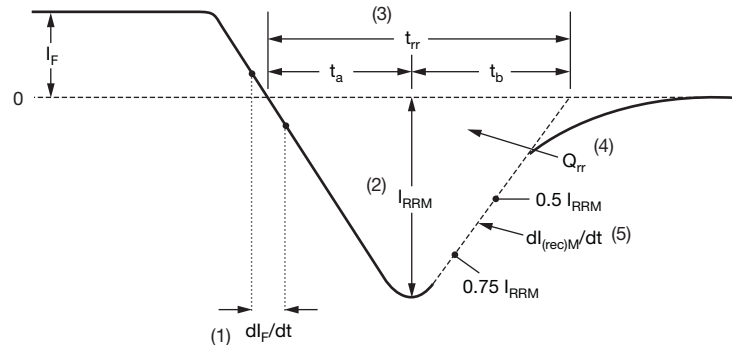


Fig. 8 - Typical Stored Charge vs. di_F/dt

Note

- (1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
 Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 8);
 Pd_{REV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = Rated V_R



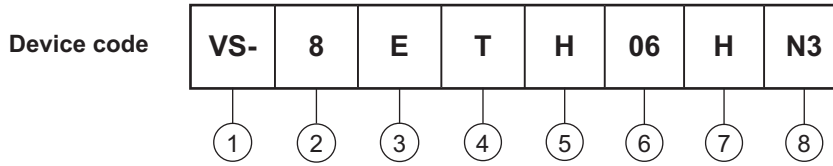
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



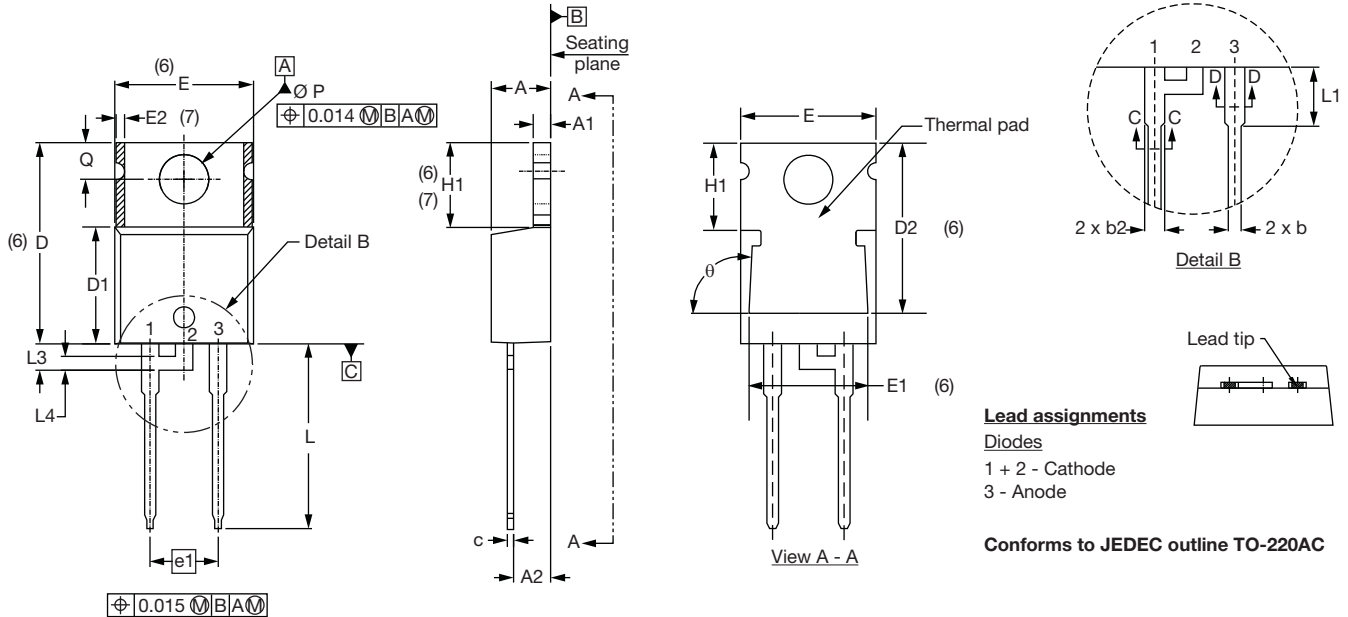
- 1** - Vishay Semiconductors product
- 2** - Current rating (8 = 8 A)
- 3** - E = single diode
- 4** - T = TO-220, D²PAK
- 5** - H = hyperfast recovery
- 6** - Voltage rating (06 = 600 V)
- 7** - H = AEC-Q101 qualified
- 8** - Environmental digit:
N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8ETH06HN3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-220AC	www.vishay.com/doc?95221
Part marking information	TO-220ACHN3	www.vishay.com/doc?95068

TO-220AC

DIMENSIONS in millimeters and inches



Lead assignments

Diodes
 1 + 2 - Cathode
 3 - Anode

Conforms to JEDEC outline TO-220AC

SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183		E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055		E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115		e	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040		e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4	H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068		L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4	L1	3.32	3.82	0.131	0.150	2
c	0.36	0.61	0.014	0.024		L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4	L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3	θ	90° to 93°		90° to 93°		
D1	8.38	9.02	0.330	0.355							
D2	11.68	12.88	0.460	0.507	6						
E	10.11	10.51	0.398	0.414	3, 6						

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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